

Title (en)

PBGA PACKAGE WITH INTEGRATED BALL GRID

Title (de)

PBGA-GEHÄUSE MIT INTEGRIERTEM KUGELRASTERRAHMEN

Title (fr)

BOITIER PBGA A GRILLE DE BILLAGE INTEGREE

Publication

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Application

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Abstract (en)

[origin: WO0068991A1] The invention concerns an integrated circuit package (5) comprising a cavity (2) wherein the integrated circuit (5) is fixed, the active surface (10) of the integrated circuit (3) being electrically connected to the package at the connection level (Nc) of a ball array (13i) on the package providing a mechanical and electrical link between the integrated circuit (5) and a printed circuit card whereon the package is to be assembled. The invention is characterised in that it comprises a rigid and electrically neutral additional layer (14) directly mounted on the connection level (Nc) of the integrated circuit (5) and the balls (13i), and contains the balls (13i). The invention is useful in particular for connections of BGA and PBGA packages.

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Citation (search report)

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